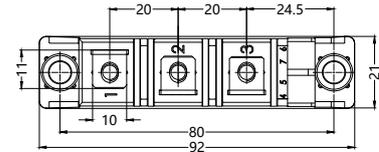
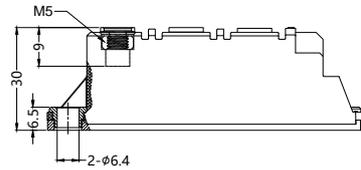
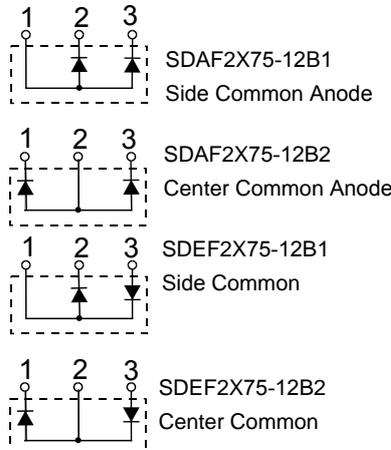
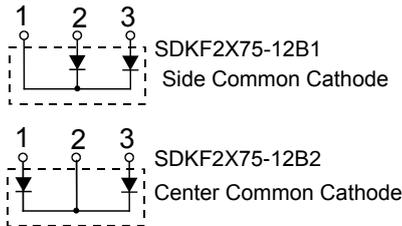


SDKF2x75-12B SDEF2x75-12B SDAF2x75-12B

Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules



Dimensions in mm (1mm=0.0394")



	VRSM V	VRRM V
SDKF2x75-12B1	1200	1200
SDKF2x75-12B2	1200	1200

	VRSM V	VRRM V
SDAF2x75-12B1	1200	1200
SDAF2x75-12B2	1200	1200

	VRSM V	VRRM V
SDEF2x75-12B1	1200	1200
SDEF2x75-12B2	1200	1200

Symbol	Test Conditions	Maximum Ratings	Unit
IFRMS	T _C =75°C	107	A
IFAVM	T _C =75°C; rectangular, d=0.5	2 x 75	
IFRM	t _p <10us; rep. rating, pulse width limited by T _{VJM}	TBD	
IFSM	T _{VJ} =45°C	t=10ms (50Hz), sine t=8.3ms (60Hz), sine	A
	T _{VJ} =150°C	t=10ms(50Hz), sine t=8.3ms(60Hz), sine	
I ² t	T _{VJ} =45°C	t=10ms (50Hz), sine t=8.3ms (60Hz), sine	A ² s
	T _{VJ} =150°C	t=10ms(50Hz), sine t=8.3ms(60Hz), sine	
T _{VJ} T _{stg} T _{Hmax}		-40...+150 -40...+125 110	°C
P _{tot}	T _{case} =25°C	280	W
V _{ISOL}	50/60Hz, RMS t=1min I _{ISOL} ≤1mA t=1s	3000 3600	V~
M _d	Mounting torque (M5) Terminal connection torque (M5)	2.50-4/22-35 2.50-4/22-35	Nm/lb.in.
ds	Creeping distance on surface	12.7	mm
dA	Strike distance through air	9.6	mm
a	Maximum allowable acceleration	50	m/s ²
Weight		108	g



SDKF2x75-12B G8 9 : &l +) !%&6 G8 5 : &l +) !%&6

Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

Symbol	Test Conditions	Characteristic Values		Unit
		typ.	max.	
I _R	T _{VJ} =25°C; V _R =V _{RRM}		2	mA
	T _{VJ} =25°C; V _R =0.8·V _{RRM}		0.5	
	T _{VJ} =125°C; V _R =0.8·V _{RRM}		34	
V _F	I _F =75A; T _{VJ} =125°C		1.85	V
	T _{VJ} =25°C		2.17	
	I _F =225A; T _{VJ} =125°C		2.58	
	T _{VJ} =25°C		2.64	
V _{TO}	For power-loss calculations only		1.48	V
r _T			3.65	m
R _{thJH} R _{thJC}	DC current DC current		0.550 0.450	K/W
t _{rr} I _{RM}	I _F =150A; T _{VJ} =100°C V _R =600V; T _{VJ} =25°C -di/dt=200A/us; T _{VJ} =100°C	250	300 22 33	ns A A

FEATURES

- * International standard package
- * Copperbase plate
- * Glass passivated chips
- * Short recovery time
- * Low switching losses
- * Soft recovery behaviour
- * UL File NO.E310749
- * RoHS compliant

APPLICATIONS

- * Antiparallel diode for high frequency switching devices
- * Free wheeling diode in converters and motor control circuits
- * Inductive heating and melting
- * Uninterruptible power supplies (UPS)
- * Ultrasonic cleaners and welders

ADVANTAGES

- * High reliability circuit operation
- * Low voltage peaks for reduced protection circuits
- * Low noise switching
- * Low losses



Sirectifier®

SDKF2x75-12B G8 9: &I +) !%&6 G8 5: &I +) !%&6

Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

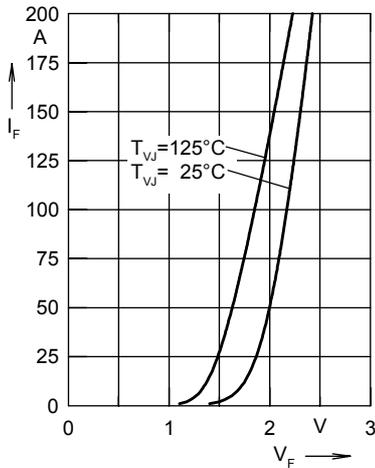


Fig. 1 Forward current I_F versus voltage drop V_F per leg

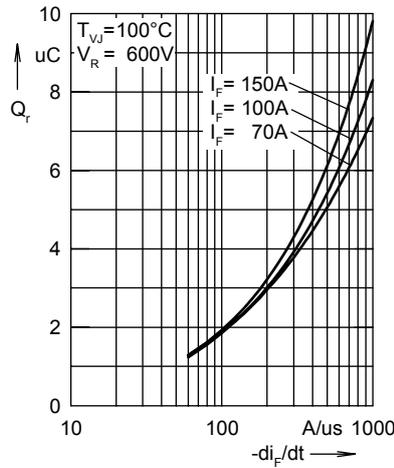


Fig. 2 Reverse recovery charge Q_r versus $-di_F/dt$

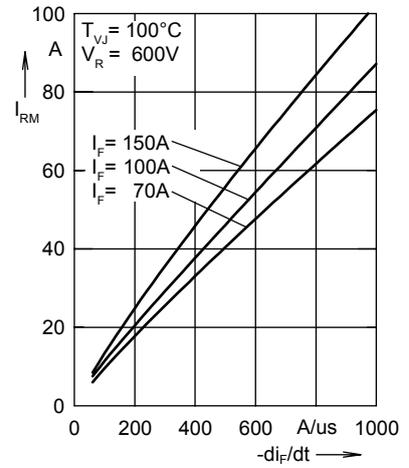


Fig. 3 Peak reverse current I_{RM} versus $-di_F/dt$

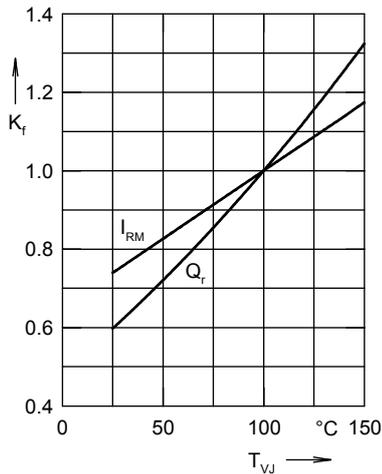


Fig. 4 Dynamic parameters Q_r , I_{RM} versus junction temperature T_{VJ}

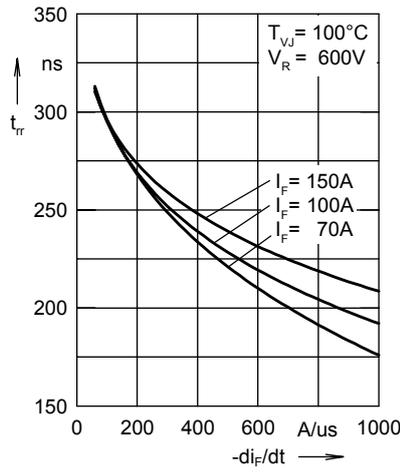


Fig. 5 Recovery time t_{tr} versus $-di_F/dt$

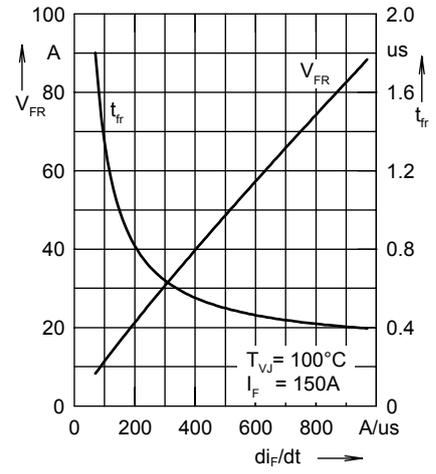


Fig. 6 Peak forward voltage V_{FR} and t_{tr} versus di_F/dt

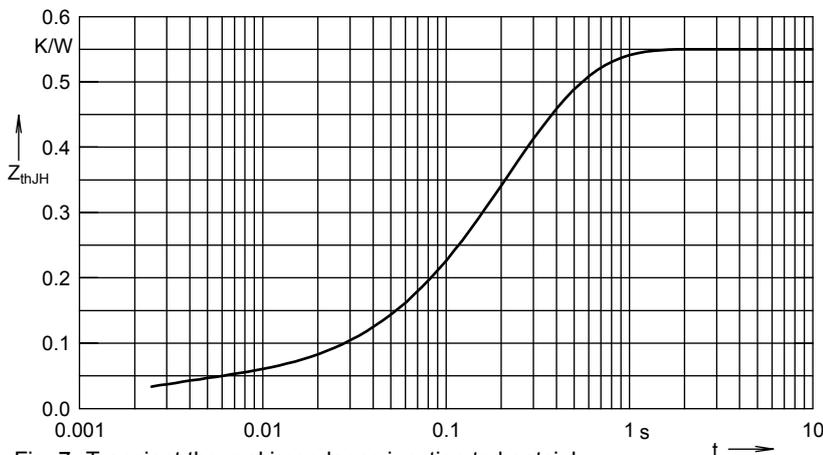


Fig. 7 Transient thermal impedance junction to heatsink

Constants for Z_{thJH} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.037	0.002
2	0.138	0.134
3	0.093	0.25
4	0.282	0.274